

SF325B Anti-ion Migration type bonding film

特点

● 粘接强度高。

- 不含卤素, 阻燃性达到UL94 VTM-0级。
- 优秀的耐热性、耐化学性和电性能。
- 优异的耐离子迁移性,不长枝状结晶。
- 溢胶量低,加工性好,适于快速压合和传统压合。
- 满足RoHS指令要求,不含铅、汞、镉、六价铬、 多溴联苯、多溴联苯醚等。

FEATURES

- High bonding strength.
- Halogen free, Flammability UL94 VTM-0.
- Excellent soldering reliability, chemical resistance and electrical properties.
- Excellent anti-ion Migration, no dendrite.
- Low adhesive flowing, good processability, suitable for both fast and traditional lamination style.
- Compatible with EU RoHS directive, free of Pb,Hg, Cd,Cr⁶⁺,PBB,PBDE, etc..

性能表 GENERAL PROPERTIES

| 州 邰 而 日 | 试验处理条件 | 单位 Unit | 性能数据 Property Data | | |
|--------------------------------------|--------------------------------------|------------|----------------------|-------------------|-----------------|
| 性能项目 Test Item | Treatment | | IPC 标准值 [*] | 典型值 Typical Value | |
| | Condition | | Standard | SF325B 15 | SF325B 25 |
| 溢胶量 | А | mm | | <0.15 | <0.15 |
| Resin Flow | A | mm | - | <0.15 | <0.15 |
| 剥离强度 1 | А | N/mm | ≥0.44 | 1.4 | 1.7 |
| Peel Strength (90°) ¹ | 288℃,5s | | ≥0.44 | 1.3 | 1.6 |
| 热应力 ¹ | 200°⊂ 20a | | | 无分层、无起泡 | 无分层、无起泡 |
| Thermal Stress ¹ | 288° ℃, 20 s | - | | No delamination | No delamination |
| 耐化学性(剥离强度保持率) Chemical Resistance | After Chemical Exposure 暴露化学品后 | % | ≥80 | >90 | >90 |
| 阻燃性 Flammable resistent | А | - | VTM-0 | PASS | PASS |

注释 Explanation: 1. 与铜箔光面和 PI 膜压合再固化后测试。Testing after laminating with shining side of copper foil and PI film in suitable condition.

* Certified to IPC-4203/20 Unsupported polyester adhesive

应用领域

多层挠性印制板和刚挠性印制板等用粘接膜。

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APPLICATIONS

Multi-layer FPC and rigid-flex PCB, etc..

SF325B 耐离子迁移型胶膜

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产品规格代码描述 Product Code Description

<u>SF325B 13</u>

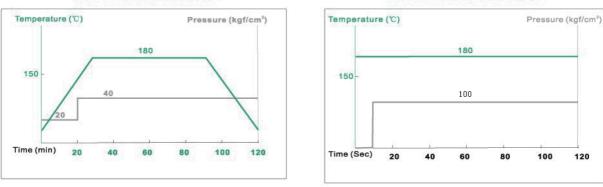
胶粘剂厚度 Adhesive Thickness: 13 - 13µm; 25 - 25µm 生益胶膜产品编号 Shengyi Bonding Film Designation

<u>常规产品表 SPECIFICATIONS OF STANDARD PRODUCTS</u>

| 产品规格 | 胶粘剂厚度 | 应用领域 | |
|----------------|-------------------------------|---------------------|--|
| Specifications | Adhesive Thickness (μ m) | Applications | |
| SF325B 13 | 13 | 多层板、刚挠结合板等 | |
| SF325B 25 | 25 | Multi-layer FPC and | |
| SF325B 40 | 40 | rigid-flex PCB etc. | |

压板推荐 PRESS PROPOSE

HOT PRESSING CYCLE



FAST PRESSING CYCLE

传压参数根据不同设备及产品规格需作相应调整;采用快压方式,后固化条件是 160-170℃、60-90 分钟。 The parameters of hot Pressure need to be adjusted according to different equipment and product specifications. After fast press, the curing condition is 160-170℃ for 60-90min.

包装 PURCHASING INFORMATION

产品宽度250+2/-0mm或500+2/-0mm,每卷100+2/-0米;其它规格、尺寸可根据客户要求而定。 SF325B is supplied in rolls and standard width of 250+2/-0mm or 500+2/-0mm. Roll length is 100+2/-0m. Other sizes could be available upon request.

储存条件 STORAGE CONDITION

贮存在干燥的室内;以原始包装贮存在4-10 ℃的冷藏室里,贮存期为三个月。 Stored in the room of dryness. Three months when stored in the original packaging at 4-10 ℃. \mathbb{Z}